

and weight. The Examiner has not pointed to any place in the references which would indicate either that the manufacturing costs or weight of either device would be improved by using a flexible substrate. Neither of the cited references are concerned with weight or reducing manufacturing costs through the use of a cheaper or more flexible substrate. Hosokawa is concerned with increased light emission efficiency. There is no mention of cost or weight, no less that these factors would be improved by utilizing a flexible substrate. Hence, Hosokawa does not provide any motivation for choosing a flexible substrate. Dingwall does not utilize flexible substrates at all. In fact, Dingwall states that glass substrates should be used to reduce cost.

Finally, in addition to showing the elements of the invention, the references must show that there is a reasonable expectation of success in combining these elements. Amgen Inc. v. Chugai Pharmaceutical Co. Ltd., 18 USPQ2d 1016, 1022 (CA FC 1991). As pointed out in the specification of the present application, thin plastic substrates are permeable to water, and hence, require a sealing layer to prevent water and oxygen from reaching the reactive materials used for the cathodes of the OLEDs. Accordingly, such materials would not normally be used in an OLED.

The above amendments to Claims 3 and 8 make it clear that the array of OLEDs is flexible. It is the flexibility of the array that provides advantages when the OLED layer is bonded to the driving transistor layer. By assuring good bonding between all of the OLED-transistor pairs, the present invention improves yield, and hence, manufacturing costs.

The Examiner indicated that Claims 4-7 and 9-12 would be allowed if re-written in independent form. The above amendments to Claims 4 and 9 place these claims in independent form with all of the limitations of the base claims.

If the Examiner has any questions with respect to this application, please feel free to contact Applicant's attorney at the telephone number indicated below.

I hereby certify that this paper (along with any others attached hereto) is being deposited with the United States Postal Service as first class mail with sufficient postage on

the date signed below in an envelope addressed to: Hon. Assistant Commissioner of Patents,
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Respectfully Submitted,

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